



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSZ16DN25NS3 G	Issued	24. February 2022
MA#	MA005709194		
Package	PG-TSDSON-8-38	Weight*	36.10 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.902	2.50	2.50	24978	24978
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		98	
	non noble metal	zinc	7440-66-6	0.014	0.04		392	
	non noble metal	iron	7439-89-6	0.283	0.78		7849	
	non noble metal	copper	7440-50-8	11.505	31.87	32.70	318698	327037
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	764	764
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1029	
	plastics	epoxy resin	-	1.913	5.30		53001	
	inorganic material	silicondioxide	60676-86-0	16.625	46.06	51.46	460545	514575
leadfinish	non noble metal	tin	7440-31-5	0.370	1.03	1.03	10251	10251
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2238	2238
solder	non noble metal	tin	7440-31-5	0.021	0.06		594	
	noble metal	silver	7440-22-4	0.027	0.07		743	
	non noble metal	lead	7439-92-1	1.024	2.84	2.97	28374	29711
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			27	
	non noble metal	zinc	7440-66-6	0.004	0.01		109	
	non noble metal	iron	7439-89-6	0.078	0.22		2171	
	non noble metal	copper	7440-50-8	3.182	8.81	9.04	88139	90446
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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